

What is claimed is:

1. A method for packaging a semiconductor device, comprising the steps of:

5 (a) forming a plurality of grooves on an upper surface of a substrate;

(b) attaching a heat sink on the substrate;

(c) attaching a chip to the substrate by using an adhesive;

10 (d) wire-bonding the substrate and the chip; and

(e) encapsulating and sealing the substrate and the chip by using an epoxy molding compound.

2. The method of claim 1, wherein at least one surface of
15 the heat sink is exposed to the atmosphere.